Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.015”**



**.019”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: E = .0048”**

 **B = .0034”**

**Backside Potential: COLLECTOR**

**Mask Ref: 485**

**APPROVED BY: DK DIE SIZE .015” X .019” DATE: 1/26/22**

**MFG: CHRYSTALONICS THICKNESS .000” P/N: 2N2432A**

**DG 10.1.2**

#### Rev B, 7/1